Special Issue

Three-Dimensional Display Technologies

Message from the Guest Editors

Three-dimensional (3D) displays are considered the next generation of displays with an enormous global market. Three-dimensional displays, when compared with conventional two-dimensional displays, can present more information, such as depth and occlusion, thereby greatly enhancing the interactivity and selectivity of information. Thanks to the rapid development in computer science, electronic devices, optics and related fields, 3D displays have hit their stride in recent years. The emergence of the metaverse and AR/VR also advocates for the application of 3D displays. Currently, there are substantial research-and-development activities by academia and industry in this field. Accordingly, this Special Issue seeks to showcase research papers, short communications, and review articles that focus on: (1) acquisition, display, and applications of 3D information; (2) image processing for 3D display applications; (3) 3D display devices, including spatial light modulators and digital micromirror devices; and (4) AR/VR display.

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Deadline for manuscript submissions

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